

LISTING OF THE CLAIMS

1-5. (Cancelled)

6. (Previously presented) A packaged photosensor device, comprising:

a first photosensor, said first photosensor comprising first electrical connections;

a second photosensor, said second photosensor comprising second electrical connections; and

a clear plastic package supporting and enclosing said first and second photosensors, said clear plastic package comprising third electrical connections along an edge perimeter, said third electrical connections being electrically coupled to said first and second electrical connections, wherein said clear plastic package is transparent in all directions and said first and second photosensors are configured to receive light from at least two opposite sides of said clear plastic package.

7. (Cancelled)

8. (Previously Presented) A method of packaging an imager device, comprising:

providing an imager device;

forming a clear plastic quad flat package for said imager device, wherein said imager device is totally encased within said clear plastic quad flat package;

forming electrical connections between a perimeter of said clear plastic quad flat package and said imager device;

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wherein said imager device is positioned to receive light that passes through said clear plastic quad flat package from any of a plurality of different incoming angles and through different surfaces of said clear plastic quad flat package.

9 and 10. (Cancelled)

11. (Previously presented) A method of packaging an imager device, comprising:

providing a first image sensor;

providing a second image sensor;

forming a clear plastic package totally enclosing said first image sensor and said second image sensor; and

providing electrical connections between said first and second image sensors and a perimeter of said clear plastic package;

wherein said first and second image sensors are positioned to receive light that passes through said clear plastic package, said first image sensor being positioned to acquire light from a first direction and said second image sensor being positioned to acquire light from a second direction different from said first direction.

12. (Previously presented) An image sensor, comprising:

a first image sensor;

a second image sensor;

a third image sensor; and

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a clear plastic package enclosing said first, second, and third image sensors, said clear plastic package and said first, second, and third image sensors configured for acquiring light through a first side, a second side, and a third side of said clear plastic package respectively, wherein said first, second, and third sides of said clear plastic package are different sides.

13. (Previously presented) A sensor as in claim 12, wherein said clear plastic package has a perimeter surrounding said first, second, and third image sensors, said perimeter including and edge comprising electrical connections coupled to said first, second, and third image sensors.

14. (Cancelled)

15. (Previously presented) An image sensor as in claim 12, wherein said first, second, and third image sensors are CMOS image sensors.

16. (Previously presented) An image sensor as in claim 12, wherein said first, second, and third image sensors acquire said image using photogates.

17 and 18. (Cancelled)

19. (Previously presented) An imager device, comprising:

a clear package, said clear package comprising an outer perimeter and an internal cavity defined within said outer perimeter, said outer perimeter comprising a plurality of first electrical connections; and

an imager die within said internal cavity, said imager die comprising an image sensor and a plurality of second electrical connections coupled to said plurality of first electrical connections,

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wherein said clear package completely surrounds said imager die and is transparent in all directions.

20. (Previously presented) An imager device as in claim 19, wherein said clear package is a quad flat package.

21. (Previously presented) An imager device as in claim 19, wherein said clear package comprises acrylic.

22. (Previously presented) An imager device as in claim 19, wherein said image sensor is a CMOS imager array.

23. (Previously presented) An imager device as in claim 19, wherein said plurality of first electrical connections extends around said perimeter.

24. (Previously presented) An imager device as in claim 19, further comprising a window configured to block photons from said image sensor.

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